



- Reduces Corrosion
- Quick Installation
- Dust Free

# CONDUFORM™

## Protecting networks and assets

**ConduForm™** is a dust free, conductive carbonaceous backfill material that is installed as a liquid and cures as a solid. **ConduForm™** is designed for applications where overburden is shallow or non-existent. It provides superior corrosion and theft protection. It can be poured on exposed rock surfaces to protect conductors and improve grounding where trenching is not possible. With an expected in-service lifetime that is up to 20x the industry standard, electrode corrosion is virtually eliminated. **ConduForm™** offers many advantages:

- Pourable – no need to transfer to mixing container
- 99.9% reduction in corrosion of copper
- Environmentally friendly
- Extends the life of the grounding system
- Liquid installation adheres well to native material
- Adheres to bedrock and other bare surfaces
- Cures as a black impermeable solid

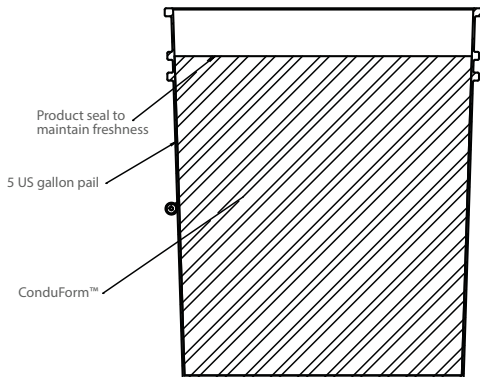


**ConduForm™** is a low slump, formable product that sets up within 3 hours of installation and forms a strong bond to the native material. It is an environmentally friendly solution that can withstand freeze-thaw cycling and helps to prevent theft and accidental damage of the conductor. It is sold in a 5 US gallon container.

## Applications

- Grounding on bedrock.
- Rocky shoreline grounding.

## Product Specifications



### Properties

#### Appearance

#### Odor

#### Permeability to Water

#### Hygroscopic Property

#### Resistivity

#### Electrolytic Corrosion Resistance

#### Freeze-Thaw Withstand

### Typical Value

Cured: Black Solid

Uncured: Dark Blue Slurry (granular)

Slight, Sweet Odor

$6.5 \times 10^{-6}$  cm/s (ASTM 5084)

34%

20  $\Omega$ ·cm

99.9%

> 25 Years (testing ongoing)

*Values subject to change.*

Updated: 6/25/2018